

MacuSpec™ PPR 200

Electrolytic Copper Metallization

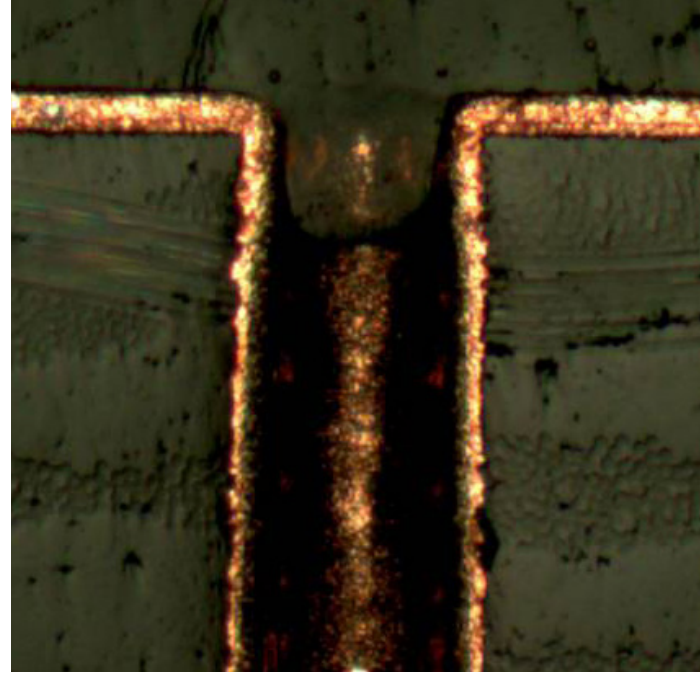
Thickness Uniformity that Pays for Itself

MacuSpec PPR 200 is the electroplating process trusted worldwide by fabricators that demand precise thickness uniformity and overall productivity unattainable by conventional acid copper plating. Designed to work more effectively on today's multilayer PCB's, it can easily meet the most challenging plating specifications.

Part of MacDermid Alpha's family of electrolytic copper plating processes, MacuSpec PPR 200 delivers a more consistent electrolytic deposit in a shorter amount of time than is possible with traditional direct current methods, thereby enabling users to increase overall output. It allows plating of a desired thickness in the center of the hole while plating less on the outer surface of the printed circuit board, greatly reducing the consumption of copper anodes and allowing for thinner dry film resists. Uniform copper distribution allows a reduction in dry film thickness, resulting in lower operating costs. MacuSpec PPR 200 successfully plates high aspect ratio through-holes and blind microvias simultaneously, without the need for multiple plating cycles. Its superior throw into high-aspect ratio through-holes can reduce plating time up to 70%.

KEY FEATURES

- Exceptional thickness uniformity
- Reliable thermal cycle performance
- Superior throw into vias: up to 70% cycle time reduction
- Reduced copper anode consumption
- The right choice for today's thicker, high density panels
- High volume productivity at the lowest cost of ownership
- Dry film resist thickness savings



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Achieve Your Plating Goals While Minimizing Cycle Time

MacDermid Alpha, a leader in electroplating technology, offers **MacuSpec PPR 200** as the optimal solution for fabricators that require thickness uniformity at the lowest possible cost. With superior throwing power into blind microvias and high aspect ratio holes, MacuSpec PPR 200 is the perfectly engineered alternative to conventional acid copper plating.

